

6P 2823

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Attorney Docket No.: ROH-0026

S. UEDA

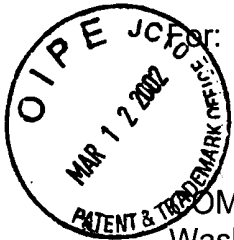
Application No.: 09/665,663

Examiner: W. D. Coleman

Filed: September 20, 2000

Art Unit: 2823

For: SEMICONDUCTOR CHIP AND METHOD OF PRODUCING THE SAME



## AMENDMENT TRANSMITTAL

COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

Date: March 12, 2002

Sir:

Transmitted herewith is an Amendment in the above-identified application.

☒ No additional fee is required.

The fee has been calculated as shown below

CLAIMS AS AMENDED							
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID	PRESENT EXTRA	SMALL ENTITY RATE		OTHER THAN A SMALL ENTITY	ADDITIONAL FEE
TOTAL CLAIMS	10 MINUS	20 =	0	X \$9	OR	\$18	\$0.00
INDEP. CLAIMS	4 MINUS	4 =	0	X \$42	OR	\$84	\$0.00
Fee for Multiple Dependent Claims \$140/\$280					OR		
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT							\$84.00

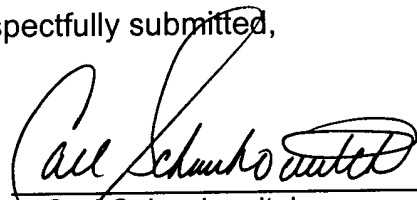
- ☐ A Letter to the Official Draftsperson is enclosed.
- ☐ An Associate Power of Attorney and Change of Name and Address is enclosed.
- ☐ Charge \$\_\_\_\_\_ to Deposit Account No. 18-0013. A duplicate copy of this sheet is enclosed.

- ☐ Any prior general authorization to charge an Issue Fee under 37 C.F.R. 1.18 to Deposit Account No. 18-0013 is hereby revoked. The Commissioner is hereby authorized to charge any additional fees under 37 CFR 1.16 and 1.17 which may be required during the entire pendency of this application, or to credit any overpayment, to Deposit Account No. 18-0013. A duplicate copy of this sheet is enclosed.
- ☐ Charge \$ \_\_\_\_\_ to Deposit Account No. 18-0013 to cover the Extension fee for response within \_\_\_\_\_ month(s).
- ☒ Applicant's undersigned attorney may be reached by telephone in our Washington D.C. Office at (202) 955-3750.

All correspondence should be directed to our below listed address.

Respectfully submitted,

By:

  
Carl Schaukowitch  
Reg. No. 29,211

**RADER, FISHMAN & GRAUER PLLC**  
1233 20<sup>th</sup> Street, N.W. Suite 501  
Washington, D.C. 20036  
Tel: (202) 955-3750  
Fax: (202) 955-3751  
Customer No. 23353

Enclosure(s):      Amendment Under 37 C.F.R. §1.111  
                            Claim to Priority under 35 USC 119  
                            Priority Document (Japanese Patent Appl. No. 11-265744)

RECEIVED  
MAR 20 2002  
TC 2800 MAIL ROOM

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

Attorney Docket No.: ROH-0026

S. UEDA

Application No.: 09/665,663

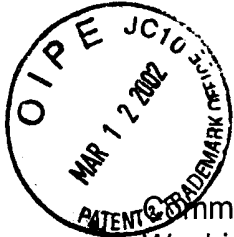
Examiner: W. D. Coleman

Filed: September 20, 2000

Art Unit: 2823

For: SEMICONDUCTOR CHIP AND METHOD OF PRODUCING THE SAME

**AMENDMENT UNDER 37 C.F.R. §1.111**



Commissioner for Patents  
Washington, DC 20231

Date: March 12, 2002

Sir:

In response to the Office Action dated December 21, 2001, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please amend claims 3, 5, 6 and 7 as set forth below in clean form. Additionally, in accordance with 37 CFR 1.121(c)(1)(ii), the amended claim(s) is/are set forth in a marked-up version in the page(s) attached to this Amendment.

3. (Amended) The semiconductor chip according to claim 2, further comprising

A1  
an internal connection pad which is formed by partially exposing said the internal wiring from said surface protective film in a portion of different from said external connection pad, and

an electrical contact projection formed in a raised state on the internal connection pad using a metal material having oxidation resistance in order to make electrical connection to the said solid device.

A2  
5. (Amended) The semiconductor chip according to claim 3, wherein